

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2757243

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SOON SENG KANG	03/03/2014
RECEIVING PARTY DATA	
Name:	ROCKWELL AUTOMATION ASIA PACIFIC BUSINESS CTR. PTE., LTD.
Street Address:	2 CORPORATION ROAD
Internal Address:	CORPORATION PLACE
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	618494
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14190726
CORRESPONDENCE DATA	
Fax Number:	(216)363-9001
Phone:	2163639000
Email:	cschweter@faysharpe.com
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>	
Correspondent Name:	STEVEN HAAS
Address Line 1:	1228 EUCLID AVENUE, 5TH FLOOR
Address Line 2:	THE HALLE BUILDING
Address Line 4:	CLEVELAND, OHIO 44115
ATTORNEY DOCKET NUMBER:	13AB074-US/ROKZ200118US01
NAME OF SUBMITTER:	DANIEL R. LING
Signature:	/Daniel R. Ling/
Date:	03/07/2014
Total Attachments: 3 source=DOC#page1.tif source=DOC#page2.tif source=DOC#page3.tif	

PATENT

DEED OF ASSIGNMENT

THIS DEED made the third day of March two thousand and fourteen (2014)
BETWEEN,

Soon Seng Kang
Block 28C, #34-57, Dover Crescent,
Singapore 133028

[hereinafter referred to as "the Assignor"]

AND

Rockwell Automation Asia Pacific Business Ctr. Pte., Ltd.
2 Corporation Road, Corporation Place,
Singapore 618494

[hereinafter referred to as "the Assignee"]

WHEREAS the Assignor warrants that the Assignor is the inventor of an invention relating to an invention entitled "**Slice-IO Housing With Side Ventilation**" [hereinafter referred to as "the Invention"], the subject of Singapore Patent Application No. **201309439-6**, filed **December 19, 2013**, including the designation of the United States of America, and also the subject of U.S. Application Serial No. **14/190,726**, filed **February 26, 2014** [hereinafter referred to as "the Application"]

AND WHEREAS the Assignor has agreed to assign to the Assignee and the Assignee desires to take assignment of all rights, title and interest of the Assignor in and to the Invention and the Application,

NOW THIS DEED WITNESSETH

1. In consideration of the sum of one dollar (\$1) and other good and valuable consideration receipt of which is hereby acknowledged by the Assignor, the Assignor hereby assigns to the Assignee all of his rights, title and interest in and to the Invention and the Application including:

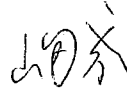
- (a) all rights and powers to make one or more applications for Letters Patent or other form of protection in the name of the Assignee in Singapore, the United States of America and in any other country of the world in respect of the Invention, and all rights, title and interest in and to any Letters Patent or other form of protection to mature from any such application,

- (b) the rights and powers to prosecute the Application and all rights, title and interest in and to any Patent or Patents granted thereon together with any extension of the term of any such Patent or Patents as may be granted, SAVE THAT nothing in this Deed shall prevent the filing or proceeding of an Application to which this Deed relates, in the name of the Assignor or Inventor where such filing or proceeding of such Application is beneficial to the interests of the Assignee
 - (c) the rights and powers to seek protection in countries other than Singapore by way of Patent, Petty Patent, Utility Model, Design Patent or other appropriate form of protection for the Invention, by way of application(s) for such protection made to the appropriate authorities in such other country or countries as the Assignee in its complete discretion may elect, whether or not any such foreign application(s) be made claiming International Convention priority from the Application hereby assigned
 - (d) any Copyright owned by the Assignor in and to any drawings relating to the subject matter of the Invention together with the rights and powers such as subsist at the date of this Deed
 - (e) to apply for registration of Copyright, Design, Design-Patent or like protection in the name of the Assignee in Singapore and in any other country of the world in respect of the subject matter of the said drawings and to any registration of Copyright, Design-Patent or like protection which matures from any such application, together with the rights to sue in respect of any infringement of that Copyright which may have occurred before the date of this Deed
2. The Assignor agrees, at the expense of the Assignee, to sign, execute and deliver all documents, forms and papers reasonably required to be produced or obtained by the Assignee in connection with any application for Letters Patent or other form of protection for the subject matter of the Invention, in Singapore or elsewhere.

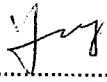
IN WITNESS WHEREOF the Assignor and Assignee executed this Deed the day and year first hereinbefore written.

ASSIGNOR

SIGNED, SEALED and DELIVERED
By the said **Soon Seng Kang**
in the presence of:



.....


..... Yong Hoek Guan
(Witness)

ASSIGNEE

FOR AND ON BEHALF OF
By the said **Rockwell Automation Asia
Pacific Business Ctr. Pte., Ltd.**

in the presence of:

.....

.....
(Witness)